

Contents

Keynote presentations	9
KN1 Evelyn Napetschnig 10 Golden Rules of Chip- Package- Board Interactions	9
KN2 Franz Röhrli Technological Status Quo for High-end RF Printed Circuit Board Development at Rohde & Schwarz	10
KN3 John H. Lau Chiplet Design and Heterogeneous Integration Packaging	11
KN4 Vaclav Wirth Soldering defects and their arduous solution in PCB assembly at Rohde & Schwarz	12
KN5 Nihal Sinnaduraj Contrasting Reliable Systems – Automotives and Mobiles	13
KN6 Vladimir Sitko Component packages and their influence on the climatic reliability of assemblies	14
KN7 Jakub Altmann AI in production – Magic AOI	15
A - New Materials, Components and Processes	16
A2 Martin Janda, David Kalas, Karel Sima Towards Additively Manufactured Alumina Substrates for Printed Electronics Applications	16
A19 Iva Králová, Vasyl Babets, Jonáš Uricár Analysis of Composite BiSn Solder Paste Doped by Titanium Dioxide Nanoparticles	18
A22 Jonáš Uricár, Dominik Pilnaj, Josef Sedláček 3D printing Conductive Pastes Based on Polystyrene/Graphite Composite	20
A36 David Michal, Jan Reboun The Effect of Oxide Reduction Using Formic Acid Vapours on The Thickness of The Conductive Layer	22
A44 Maria Vesna Nikolic, Zorka Z. Vasiljevic, Milena P. Dojcinovic NTC Thermistor Ferrite Composite for Temperature Sensing with Reduced Humidity Influence	24
A45 Radek Tucek, Lukáš Vojtech Effect of electro(less) plating on mechanical and geometric properties of polymer-metal structures based on 3D printed models	26

A48	Adam Urban, Silvan Pretl, Martin Janda Stretchability of Printed Conductive Structures for Thermoformable Structural Electronics	28
A49	Sergiu Cadar, Dorin Petreus, Toma Patarau Design of a Flat Coil Electrothermal Vaporization Device for Inductively Coupled Plasma Optical Emission Spectrometry	30
A58	Kok Siong Siah, Umang Bharatkumar Ramaiya, Felix Häußler, Hüseyin Erdogan, Jörg Franke Additively Printed Heating Structure for Radome De-icing Application	32
A71	Christoph Hecht, Mario Sprenger, Jörg Franke Laser powder bed fusion of titanium alloyed copper powder for power electronic substrates	34
A87	Rebeka Kovács, Attila Bonyár Printed Piezoelectric Harvester for Integration in a Wearable Energy Storage Device	36
A104	Olga Rac-Rumijowska, Piotr Pokryszka, Patrycja Suchorska-Wozniak, Katarzyna Kaczkowska, Iwona Karbownik, Tomasz Rybicki Flexible Frequency Selective Surfaces	38
A113	Christian Voigt, Johannes Dornheim, Alexander Muth, Nils Thielen, Jörg Franke Influences on the Mechanical Strength of Inkjet-Printed, Ag-Nanoparticle-Based Interconnects of Ni-Ag Finished Fine-Pitch Components	40
A118	Szymon Wójcik, Mirosław Gierczak, Kathrin Reinhardt, Andrzej Dziedzic Thick-film CuNi-Ag and CuNi-Cu thermocouples and Thermoelectric microgenerators	42
A119	Szymon Wójcik, Mirosław Gierczak, Nana Brguljan, Andrzej Dziedzic Thick-Film Thermoelectric Structures Based on Ca₃Co₄O₉-Ag and Ca_{2.7}Bi_{0.3}Co₄O₉-Ag Thermopiles	44
B - Thermal Management		46
B37	Corina Ruxandra Mitulescu, Mihai Branzei, Bogdan Mihailescu Thermal Diffusivity Determination of a Semiconductor Device	46
B55	Faisal Rehman, Dominika Dusíková, Jan Zemen A Simple and Cost-Efficient Method for Lithium-ion Battery Thermal Parameter Identification	48
C - Advanced Packaging and Interconnection Technologies		50
C11	Nithin Anujan Beena, Lukas Lorenz, Thomas Ludewig, Volker Bock Low Temperature Adhesive Die Bonding for Sensitive MEMS Dies	50
C46	Karamat Adavi, Sebastian Quednau, Xaver Müller, Karsten Meier, Hanno Platz Experimental Study of a Novel Printed Circuit Board Interconnection Technology	52
C110	Marcin Mysliwiec, Krystian Pavlov, Ryszard Kisiel Silver Sintering Application in Packaging Al Metallized Chip onto Au Metallized Substrates	54
D - Testing, Reliability and Quality Management		56

D1	HyeonMin Jeong, KyoungMin Song, KilSu Lee, Dexter Inciong Reynoso, Rabie Djemour Power Cycling Lifetime Improvement in Aluminum Wire Bonding Process	56
D3	Martin Hirman, Jiri Navratil, Tomáš Blecha, Renata Nemcokova, Viera Glombikova, Frantisek Steiner How Different Cleaning Procedures Affect Reliability of Conductive Joints on E Textiles?	58
D4	Martin Hirman, Jiri Navratil, Tomáš Blecha, Renata Nemcokova, Viera Glombikova, Frantisek Steiner Moisture Resistance Enhancing of E-Textiles	60
D7	Markéta Klimtová, Petr Veselý, Iva Králová Electrochemical Migration Resistance of Gold Surface Finishes	62
D17	Nicolae Ioan Gross, Paul Svasta Development of Sensor Emulators for Testing the Safety Mechanisms of Sensor Interfaces in Automotive Electronics	64
D21	Max Häusler, Karsten Meier, Karlheinz Bock Analysis of Electronic Modules for Construction Machines and Development of a Reliability Test Method	66
D23	Petr Veselý, Jaroslav Šenkýr, Markéta Klimtová Electrochemical Migration: What Happens If You Pour Coke into Computer	68
D24	Chengzhe Lyu, Karsten Meier, Karlheinz Bock Development of Computationally Efficient Numerical Models for Assessing the Reliability of Electronic Components under Vibration Loads	70
D32	Ali Gharaibeh, Dániel Rigler, Bálint Medgyes Electrochemical Migration: Evaluating the Effect of Fe₂O₃ Nanoparticle Incorporation on the Reliability of SAC Alloys	72
D33	Daniel Dzivy, Alena Pietrikova, Peter Hornak Effect of New Types of PCB Surface Finishes on Fractographic Morphology of Solder Joints	74
D41	Ali Dayoub, Ali Gharaibeh, Patrik Tamási, Markéta Klimtová, Iva Králová, Karel Dušek, Bálint Medgyes Effect of TiO₂ Nanoparticles Addition on the Electrochemical Migration of Lead-Free Sn-Bi Alloys	76
D50	Tomáš Chvosta, Karel Dušek, Tomáš Gurcík Occurrence of Voids in Soldered Joints for Electrical Engineering	78
D53	Joshua Depiver, Sabuj Mallik, Emeka H. Amalu Assessing Impact of Creep and Random Vibration on BGA Solder Interconnects Through Finite Element Analysis (FEA)	80
D59	Pavel Mach, Ivana Pelikánová The Use of Scatter Plot Charts for the Study of Changes in the Electrical Parameters of Conductive Adhesive Joints	82
D60	Pavel Mach, Ivana Pelikánová, Jaroslav Rohlena Effect of Post-Annealing on Electrical Parameters of Joints Formed from Conductive Adhesive	84

D61	Karel Dušek, Petr Veselý, David Bušek, Iva Králová, Markéta Klimtová, Dominik Pilnaj, Jonáš Uricár, Zbynek Plachý, Kristina Sorokina, Jan Hintermüller, Ali Dayoub	
	Influence of Reflow Temperature Profile on the Intermetallic Layers Thickness at Different Surface Finishes	86
D64	Igor Vehec, Peter Lukacs, Tomas Lenger, Lukas Garnek	
	Effect of Manufacturing Technology on Polymer Thick-film Resistors in 3D Printed Structures	88
D66	Krasimir Y. Kishkin, Dimitar D. Arnaudov, Venelin Todorov	
	Lithium-Ion Cell and Battery Testing by Spectral Analysis	90
D67	Denis Froš, Markéta Klimtová, Iva Králov	
	Effects of Thermal Cycling and PCB Substrate Type on Reliability of Solder Joints	92
D68	Zbynek Plachý, Attila Géczy, Karel Dušek	
	Board Level Underfill – Moisture Related Voids	94
D76	Peter Lukacs, Tomas Lenger, Igor Vehec	
	Electrical Properties' Stability of Flexible Carbon-Based Conductive Layers	96
D79	Dominik Pilnaj, Jonáš Uricár, Petr Veselý, Karel Dušek	
	Utilization of microextraction-gas chromatography coupled to mass spectrometry for characterization of electrotechnology materials	98
D81	Tomas Lenger, Alena Pietrikova, Peter Lukacs, Martin Jarkovsky	
	Stability of OhmegaPly Resistors with Different Shapes	100
D88	Pavel Rous, František Steiner	
	Analyzing the Impact of Surface Treatment on Solder Joint Voids	102
D94	Erik Wiss, Shiva Goud Anthati, Vlad Serea	
	The use of bending experiments for the efficient characterization of the mechanical functionality of component interconnections	104
D102	Moritz Hartleb, Peter Imrich, Johannes Zechner, Golta Khatibi	
	Adhesion measurements of polyimide to SixNy for semiconductor component applications	106
D105	Michele Galasso, Simon Schwunk, Václav Knap	
	Variations in Open Circuit Voltage of Cycle-Aged Lithium-Ion Batteries due to Silicon-Enhanced Anodes	108
D117	Piotr Marek Markowski	
	The set-up for Seebeck coefficient characterisation of film materials	110
D123	David Busek, Jonáš Uricár	
	An Expired Solder Paste vs Fresh Solder Paste: Reliability and Sustainability in Electronics Manufacturing	112
E - Process Modelling and Simulation		114
E6	Nicolae Alexandru Sârbu, Dorin Petreus	
	Intra-Day Optimal Dispatching of an Islanded Microgrid under Solar Power Uncertainty	114
E9	Oliver Krammer, Patrik Kovács	
	Modelling the Effect of Laser-Trimming on the Electrical Properties of Thick-film Resistors	116

E27	Mirela Olteanu, Dorin Petreus, Ana-Maria Petri Active balancing of Li-ion battery cells using the DC2100B-C and DC2100B-D module	118
E39	István Bozsóki, Attila Géczy, Balázs Illés Investigation of Sn grain growth in solder joints by numerical simulations	120
E43	Eliza Maria Olariu, Adelina Ioana Ilies, Horia Hedesiu Distributed System Using Synthetic Data of Lithium-ion Battery Digital Twin for Battery Diagnosis	122
E54	Stoyan Stoyanov, Tim Tilford, Yaochun Shen Reliability Meta-modelling of Power Components	124
E57	Nicoleta Stroia, Daniel Moga, Dorin Petreus, Eniko Lazar, Alexandru Lodin Optimal resource scheduling for a greenhouse powered by an islanded microgrid	126
E95	Adam Yuile, Erik Wiss, David Barth Study of Thermal Loading of Ceramic Capacitors during Reflow Soldering	128
E97	Dimitar D. Arnaudov, Krasimir Y. Kishkin, George Angelov Modelling of Battery Management System based on Switching Capacitors	130
E98	Sven Meier, Florian Töper, Jonas Gebele, Nils Thielen, Steffen Klarmann, Jörg Franke Knowledge Mining using Generative AI for Causal Discovery in Electronics Production	132
E103	Tzu-Chi Zeng, Vito Lin, Teny Shih FCCSP Warpage Scope Evaluation for 5G Product with Advanced Wafer Node	134
E107	Václav Knap, Anna Pražanová, Jan Kasper, Pavel Hrzina State-of-Charge Estimation Based on Open-Circuit Voltage Model Considering Hysteresis	136
E116	Dominika Dušíková, Jan Zemen Simulation of Electrochemical Heating in Li-Ion Batteries	138
F	Environmental and Ecological Effects in Electronics Technology	140
F12	Jakub Zdráhal, Markéta Klimtová, Iva Králová 3D Printed Circuit Boards from Recycled Plastics: Interconnection Properties	140
F18	Michael Fridrich, Anna Pražanová, Václav Knap Hydrogen in Automotive: LCA Study	142
F28	Andrea Benešová, Martin Hirman, František Steiner Towards Sustainable Electronics: Unveiling the Nexus of Circular Economy, Global Policies and Industry Impacts	144
F47	Csaba Farkas, András Csiszár, László Gál, Attila Géczy Soil Degradation of Sustainable PLA/Flax Substrates and Printed Circuit Board Assemblies	146
F65	Jan Kocí, Anna Pražanová, Václav Knap Unlocking Insights: A Systematic Survey of Material Composition in Lithium-Ion Battery Cells for Recycling Solutions	148

F74	Peter Lukacs, Tomas Lenger, Igor Vehec	
	Biodegradable Comb Sensor Based on 3D Printed Conductive Polylactic Acid	150
F92	Ioan Szabo, Andrei Tulbure, Cristian Farcas	
	Sustainability in Electronics - Testing Sensors with Polycarbonate Housing (PC) vs Poly Lactic Acid Housing (PLA)	152
F99	Gergo Havellant, Attila Géczy	
	Increasing productivity in vapour phase soldering using stack-mode	154
F108	Anna Pražanová, Zbynek Plachý, Jonáš Uricár, Václav Knap	
	Sustainability Challenges: The Circular Economy Dilemma in Lithium-Ion Battery Cell Electrochemical Discharging Processes	156
G - Nanotechnology, Nanomaterials and Nanoelectronics		158
G25	Irina Wodak, Golta Khatibi, Andriy Yakymovych, Attila Géczy	
	Iron Nanoparticle-Doped Flux: Wetting Characteristics of Flux and SAC305 Solder and Effects on Flux Viscosity	158
G73	Rostislav Rusev, Ivelina Ruskova, George Angelov, Elitsa Gieva, Rossen Radonov, Dorian Minkov	
	TCAD model of GAA Nanowire Transistor with silicon oxide/nitride/oxide dielectric	160
G75	Alexandra Borók, Attila Bonyár	
	Investigation of In-Situ Polymerization in Nanocomposites	162
G84	Nóra Tarpataki, Alexandra Borók, Attila Bonyár	
	Detection of Nucleotides Using Gold Nanoprisms Immobilized on Glass	164
G86	Rebeka Kovács, Attila Bonyár	
	Modeling the Optical Response of a Periodic Nanoparticle Arrangement with the Finite Element Method	166
G121	Shireen Zangana, Melinda Szalóki, Miklós Veres	
	Investigation of Polymer Nanocomposites Doped with Gold Nanorods and Alexa Fluor Indicator Molecules with Raman Spectroscopy	168
H - Signal Integrity and Electromagnetic Compatibility		170
H10	Jae-Ho Choi, Dong-Yoon Seo, Se-Woong Choi, Do-Hyung Kim, Jeong-hyeon Cho, Ji-Won Kim, Lee Won-Seop	
	Propagation Delay Analysis by Employing Various PCB Manufacturing Process	170
H14	Saeedeh Lotfi, Golshan Mohamadpour, Tomáš Blecha	
	A Dual-Band Wilkinson Power Divider Using Compact Lowpass Filter with Wide Suppression Band	172
H15	Saeedeh Lotfi, Golshan Mohamadpour, Tomáš Blecha	
	Design of a Quadrature Hybrid Coupler with Triple Tapered Resonators	174
H16	Sobhan Roshani, Saeed Roshani, Saeedeh Lotfi, Martin Janda	
	Design of Ultra-wide Stopband Lowpass Filter based on Compact Microstrip Resonator Cells	176
H85	Jan Handrejch, Tomáš Blecha	
	Textile-Based Flexible Coaxial Cable	178

I - Sensors, Actuators and Microsystems	180
I5 Stoyan G. Bogdanov, Nina R. Bogdanova, Elitsa Gieva Development an Ultra-Low Power “Coin” Size Sensor	180
I26 Petre Anghelescu Design and Implementation of an Electronic Encryption System based on PCA algorithm	182
I29 Milan Z. Bodic, Stanko O. Aleksic, Vladimir M. Rajs, Milica G. Kisic Thermal Junction of NTC Chip Thermistors	184
I30 Miroslav Mikolasek, Martin Kemeny, Martin Brazda, Erik Baga, Jakub Gavenda, Lukas Gardian, Matej Novak Differential thermal voltammetry for states-of-health (SOH) estimation of Li-ion batteries	186
I31 Felix Stadermann, Victoria Constance Köst, Krzysztof Nieweglowski, Karlheinz Bock Evaluation of semipermeable membranes for encapsuling gas sensors in human intestinal environments	188
I38 Irina Madalina Burcea, Rodica Cristina Negroiu, Bogdan Mihailescu, Madalin Vasile Moise, Ciprian Ionescu Realization of Cost-Effective Supercapacitors Utilising Substitutable Materials	190
I40 Michaela Radouchova, Tomáš Blecha Highly Elastic Textile Conductive Ribbons as Frequency Resonators for Wearable Strain Monitoring	192
I42 Dorin Petreus, Toma Patarau, Petre Dorel Teodosescu Modelling and Simulation of a Two-Stage Grid-Connected MPPT Inverter	194
I56 Alexandru-Florin Flutur, Septimiu Sever Pop, Vlad Bande Evaluating the Performance of Measurements Systems Using Data Processing Methods Based on Kalman Filter	196
I62 Mitar Simic Portable Device for In-Situ Cyclic Voltammetry Measurements	198
I63 Rade Tomov, Mariya Aleksandrova, Georgi Nikolov, Ivo Iliev Multifunctional Inkjet-Printed Silver Structures for Wearable Biosensors	200
I70 Madalina Pena, Gombos Andreea, Emilian Ceuca A TeraRanger One based LiDAR	202
I80 Rosen Miletiev, Rumen Yordanov, Emil Iontchev Design of navigation system with wireless connectivity	204
I82 Slavomir Kardos, Igor Vehec 3-axis Accelerometer IMU in Various Degrees of Freedom Multi-switch Button Array	206
I83 Josef Slauf, Jan Reboun Nitrogen Dioxide Sensor based on Organic Electrochemical Transistor	208
I89 Ana Cristina Davidas, Ovidiu A. Pop, Liviu Viman, Traian Petrisor Jr. Noise Measurement System Based on Cross-Correlation Method . . .	210
I96 Barbara Molnár, Attila Géczy Electronic Nose Based on AI-capable Sensor Module for Beverages Identification	212

I111	Miroslav Katanic, Dragica Pantelic, Nikola Šormaz, Vladimir Citakovic, Milica Kisic, Mirjana Damnjanovic	
	Stretchable Strain Sensor using Interdigitated Capacitor on Fabric	214
I112	Mirjana Damnjanovic, Milica Kisic, Miodrag Milutinov, Stanko Aleksic	
	Influence of Number of Turns on Common-Mode Choke’s Characteristics	216
I122	Lucian Andrei Perisoara, Irina Bristena Bacîs, Dragos Ioan Sacaleanu	
	Master-Slave BMS Architecture with CAN-bus for Inter-Cell Communication	218
J -	Educational and Information Technologies in Electronics Manufacturing	220
J90	Andrei Tulbure, Ioan Szabo, Adrian Tulbure, Eva Dulf	
	Training Cost Analysis on a Large Computer Vision Ceramic Defect Detection Model	220